

IN THE CLAIMS:

Please cancel claims 1 - 11 and replace them with the following claims. The status of the claims after amendment will be as follows:

Claims 1 - 11 (cancelled)

12. (new) A lead-free solder alloy consisting of 0.1 - 3 wt% of Cu, 0.001 - 0.1 wt% of P, greater than 0 and at most 0.5 wt% of Ni, and a balance of Sn.

13. (new) A lead-free solder alloy as claimed in claim 12 wherein the content of Ni is at most 0.3 wt %.

14. (new) A lead-free solder alloy as claimed in claim 12 wherein the content of P is 0.001 - 0.05 wt%.

15. (new) A lead-free solder alloy as claimed in claim 12 wherein the content of P is 0.001 - 0.01 wt%.

16. (new) A solder paste comprising the lead-free solder alloy of claim 12.

17. (new) A flow soldered joint formed by flow soldering a lead-free solder alloy as claimed in claim 12.

18. (new) A soldering method comprising forming a bath of molten solder of the lead-free solder alloy as claimed in claim 12 and contacting an object to be soldered with the molten solder.

19. (new) A method as claimed in claim 18 including contacting the object with a wave of the molten solder.

20. (new) A lead-free solder alloy consisting of 0.1 - 3 wt% of Cu, 0.001 - 0.1 wt% of P, greater than 0 and at most 0.1 wt% of Ge, and a balance of Sn.

21. (new) A lead-free solder alloy as claimed in claim 20 wherein the content of Ge is 0.001 - 0.1 wt%.

22. (new) A lead-free solder alloy as claimed in claim 20 wherein the total content of Ge and P is less than 0.01 wt%.

23. (new) A solder paste comprising the lead-free solder alloy of claim 20.

24. (new) A flow soldered joint formed by flow soldering a lead-free solder alloy as claimed in claim 20.

25. (new) A soldering method comprising forming a bath of molten solder of the lead-free solder alloy as claimed in claim 20 and contacting an object to be soldered with the molten

solder.

26. (new) A method as claimed in claim 25 including contacting the object with a wave of the molten solder.

27. (new) A lead-free solder alloy consisting of 0.1 - 3 wt% of Cu, 0.001 - 0.1 wt% of P, greater than 0 and at most 4 wt% of Ag, greater than 0 and at most 0.1 wt% of Ge, and a balance of Sn.

28. (new) A lead-free solder alloy as claimed in claim 27 wherein the content of Ge is 0.001 - 0.1 wt%.

29. (new) A flow soldered joint formed by flow soldering a lead-free solder alloy as claimed in claim 27.

30. (new) A soldering method comprising forming a bath of molten solder of the lead-free solder alloy as claimed in claim 27 and contacting an object to be soldered with the molten solder.

31. (new) A method as claimed in claim 30 contacting the object with a wave of the molten solder.